

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

KONISHI et al.

Atty. Ref.: 829-615; Confirmation No.

Appl. No. To be Assigned

Group:

Filed: September 11, 2003

Examiner:

For: RESIN MOLDING DIE AND PRODUCTION METHOD FOR
SEMICONDUCTOR DEVICES USING THE SAME

September 11, 2003

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

PRELIMINARY AMENDMENT

In order to place the above-identified application in better condition for
examination, please amend the application as follows: